M1 ~ M7 SMA

Surface Mount Standard Rectifiers

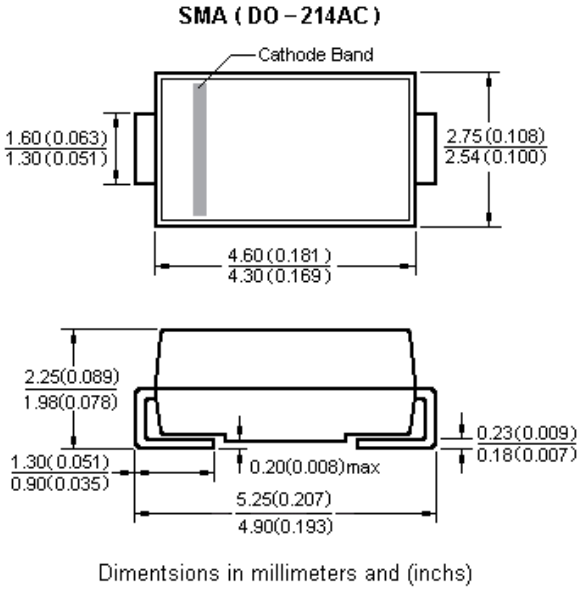
Major Ratings and Characteristics

$I_{F(AV)}$	1.0 A
V_{RRM}	50 V to 1000 V
I_{FSM}	30 A
I_R	5 μA
V_F	1.1 V
T_j max.	150 °C

SMA (DO – 214AC)

Features

- Low profile space
- Ideal for automated placement
- Glass passivated chip junction
- Low forward voltage drop
- Low leakage current
- High forward surage capability
- High temperatrue soldering：
  260℃/10 seconds at terminals
- Component in accordance to
  RoHS 2002/95/1 and WEEE 2002/96/EC



Dimentsions in millimeters and (inchs)

Mechanical Date

- Case: JEDEC DO-214AC molded plastic over glass passivated chip
- Terminals: Solder plated, solderable per J-STD-002B and JESD22-B102D
- Polarity: Laser band denotes cathode end

Maximum Ratings & Thermal Characteristics & Electrical Characteristics

(TA = 25 °C unless otherwise noted)

	Symbol	M1	M2	M3	M4	M5	M6	M7	UNIT
Maximum repetitive peak reverse voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum average forward rectified current	$I_{F(AV)}$	1							A
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	I_{FSM}	30							A
Maximum instantaneous forwad voltage at 1.0A	V_F	1.1							V
Maximum DC reverse current T_A = 25 ℃	I_R	5.0							μA
at Rated DC blocking voltage T_A = 125℃		50							μA
Typical junction capacitance at 4.0 V ,1MHz	C_J	15							p F
Thermal resistance from junction to ambient	$R_{\theta JA}$	75							℃/ W
Operating junction and storage temperature range	T_J, T_{STG}	–55 to +150							℃

M1 ~ M7 SMA

Surface Mount Standard Rectifiers

Characteristic Curves (T_A=25 ℃ unless otherwise noted)

Fig.1 Forward Current Derating Curve

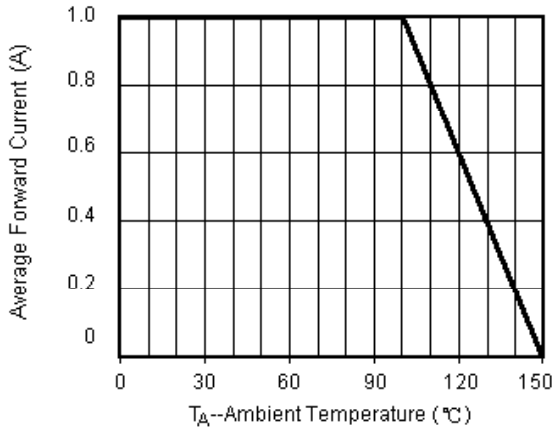


Fig.2 Maximum Non-Repetitive Peak Forward Surge Current

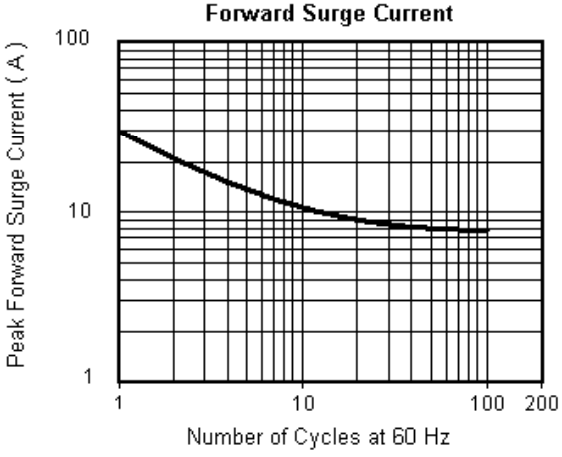


Fig.3 Typical Instantaneous Forward Characteristics

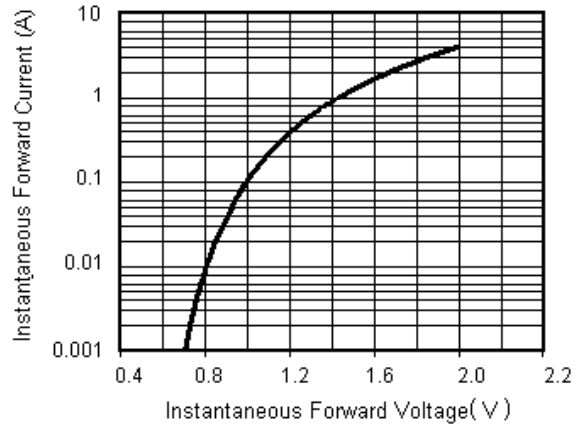


Fig.4 Typical Reverse Leakage Characteristics

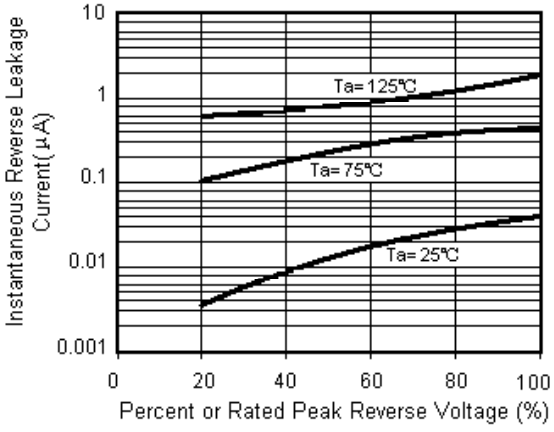


Fig.5 Typical Junction Capacitance

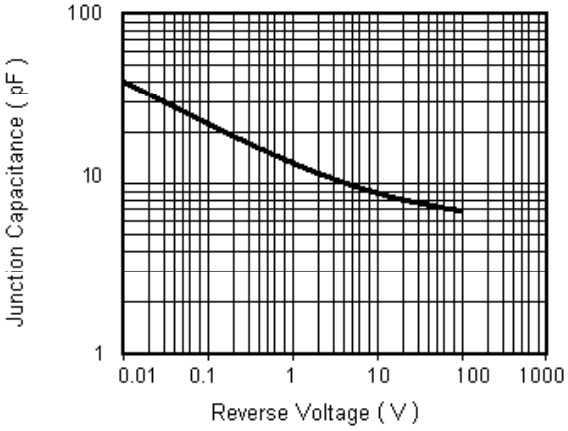


Fig.6 Transient Thermal Impedance